Thermal Expansion Measurement System by Laser Interferometer LIX series

High-accuracy thermal expansion measurements with a minimum resolution of 2 nm.

Precise expansion measurements of low-thermal expansion materials and electronic component materials can be performed. Also capable of performing expansion measurements in the film thickness direction.

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Applications

- Expansion measurements in the thickness direction of organic films
- High-accuracy expansion measurements of low-expansion glass
- Expansion measurements of seal materials

Features

- Capable of thickness direction measurements of polymer film materials 50 to 500 µm thick

A patent and a standard

Complies with JISR 3251-1995
Parallel moving sample holder (patented)

Specifications

Thermal Expansion Measurement System by Laser Interferometer LIX series		
Type	LIX-2M	LIX-2L
Measurement Properties	Thermal expansion	
Temperature Range	RT to 700 °C	-150 °C to 200 °C
Sample Size	ϕ 3 to 6 mm x 10 mm to 15 mm length, spherical finish for both ends in the length direction	
Measurement Atmosphere	Vacuum Low-pressure high-purity He gas	